

*Patent Application Serial No. 10/568,416*

**REMARKS**

Amendment of claim 1 is requested. This amendment was discussed during the interview of September 20, 2010, the Applicant having submitted an agenda proposing this amendment earlier. The Examiner is thanked for the interview.

Entry is proper because the amendment, which was suggested by the Examiner to overcome the rejection (Action, bottom of page 9), will overcome the outstanding rejection under § 103 for the reasons below. (As to the drawing objection, the Applicant is preparing a drawing change to be submitted in due course.)

**Arguments.** The Applicant understands, from the Examiner's remarks during the interview, that the rejection is based on the idea that the person of ordinary skill would have placed the clips of Takashi over *both* of the substrates of Yukio, in order to hold them together. However, Yukio itself does not suggest anything about edge attachment, and edge attachment is irrelevant to its object, namely, to prevent bulging of the front substrate due to pressure changes (see, e.g., paragraphs 0003-0006). The clips of Takashi would not help solve Yukio's mechanical problem of bulging due to internal pressure.

The rejection asserts (page 5, second paragraph) "that by having the clips pinch the substrate, the thickness can become small, thus reducing size [and] costs." With respect, there would be no reduction in costs unless something were eliminated from Yukio; adding clips would only *increase* the cost. As to making the thickness smaller, there is no evidence on the record showing that the layers of Yukio's device would be compressed. Yukio mentions only rigid materials such as PET, which would not be appreciably reduced in thickness by clips.

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The Applicant submits that the person of ordinary skill would not have added the clips of Takashi to Yukio for any mechanical reason.

Furthermore, the asserted combination would not work unless Yukio's electrical connector 120 were retained, because in Yukio the electrical connections 114, 134 are on the inner surfaces of the two substrates 110 and 130, and a clip engaging the entire unit as urged could not make any electrical contact. Therefore, the person of ordinary skill would not have added the clips of Takashi to Yukio for any electrical reason.

**Disclosure of Takashi.** During the interview, the Examiner stated that the amendment of the agenda could overcome the rejection with the submission of additional arguments against the rejection, but also said that portions of his PTO translation of the Takashi reference perhaps suggest that the Takashi clips could be put over all of the substrates, rather than only those substrates illustrated (base board 7 and substrate 4); however, the Examiner also stated that the quality of PTO translations is not so good as those obtained from Japan, and perhaps should not be relied upon. The Examiner mentioned ordering a better translation from Japan.

The undersigned attorney's foreign associate, being informed of the situation, has provided a Japanese translation of portions of Takashi, which are reproduced below; the translation portions have been put into italic type for the Examiner's easy reference. The foreign associate writes,

"As for conductive clip 13 of Takashi, Takashi describes (in the following English translations) in paragraph [0013] that *'as shown in Fig. 1, both ends of the glass substrate 4 and the wiring base board 7 are pinched with a conductive clip 13a that comprises integrated plural conductive clips 13. Each of the conductive clips 13 electrically connects the electrode leads 5*

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*and 6, which are formed on the internal face of the glass substrate 4 as the electrode terminals, with the electrode terminals 9, which are formed on the internal face of the wiring base board 7 as the electrode terminals.'*

"Further, paragraph [0014] recites that '*[s]uch a conductive clip 13 is formed by bending a metal plate of a phosphor bronze, a steel plate etc. so that the metal plate has a springy property or flexibility, and bringing a plane of the metal plate into contact with the electrode leads 5 and 6 or the electrode terminals 9. Further, by warping the conductive clip as with the conductive clip 13A in Fig. 5, the contact area with the electrode terminals can be reduced, thereby improving the flexibility and more strongly holding the glass substrate and the wiring base board.'*

"Still further, paragraph [0020] recites that '*[f]urthermore, as shown in Fig. 9 and Fig. 10, the conductive clip 13 may have an optional arrangement. More specifically, although the conductive clip 13A shown in Fig. 5 has a springy property or flexibility by having a curved portion and thereby more strongly holds the glass substrate and the wiring base board, it also has a defect in that the problem of dust on the circuit is more significant due to the small contact area with the electrodes, thereby more easily causing poor conductivity. On the other hand, the conductive clip 13B of Fig. 9 solves this problem by having two contact areas. The two contact areas may also be formed on the face in contact with the electrode terminals 9.'*

"Additionally, paragraph [0021] recites that '*[f]urthermore, the conductive clip 13C shown in Fig. 10 is configured by providing a "rubber body e" on the inner plane of the conductive clips 13, 13A or 13B. With this structure, the metal conductive clip 13C does not come in contact with the glass substrate 4 when it pinches the glass substrate 4 and the wiring*

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*base board 7 together, thereby preventing cracks on the edge of the substrate or any damage to the substrate. Thus, the conductive clip 13C has improved reliability.'*

In the translated portions above, there is no support for any inference that Takashi's text discloses more than its drawing shows.

Entry and allowance are requested.

Respectfully submitted,

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*I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office (Fax No. (571-273-8300) on September 29, 2010.*

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